

Small Signal Product

Low VF SMD Schottky Barrier Diode

FEATURES

- Low power loss, high current capability, low VF
- Surface device type mounting
- Moisture sensitivity level (MSL): 1
- Matte Tin (Sn) lead finish with Nickel (Ni) under plate
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21





SOD-123



MECHANICAL DATA

- Case: SOD-123 small outline plastic package

- Molding compound, UL flammability classification rating 94V-0

 Terminal: Matte tin plated, lead free, solderable per MIL-STD-202, Method 208 guar
High temperature soldering guaranteed: 260°C/10s

Polarity: Indicated by cathode bandWeight: 0.01 g (approximately)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS (T _A =25°C unless otherwise noted)					
PARAMETER	SYMBOL	SD103AW	SD103BW	SD103CW	UNIT
Power Dissipation	P _D		400		mW
Repetitive Peak Reverse Voltage	V_{RRM}	40	30	20	V
Reverse Voltage	V_R	28	21	14	V
Mean Forward Current @ T _L = 100°C	Ιο		350		mA
Repetitive Peak Forward Surge Current $@t \le 1.0 s$	I _{FRM}		1.5		Α
Thermal Resistance (Junction to Ambient)	$R_{\theta JA}$		300		°C/W
Junction Temperature	T _J		125		°C
Storage Temperature Range	T_{STG}		-65 to +125		°C

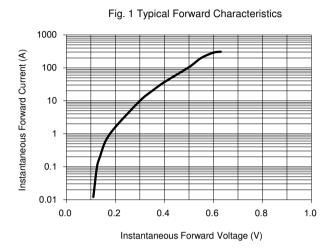
PARAN	SYMBOL	MIN	TYP	MAX	Units	
	SD103AW I _R = 10 µA		40			
Reverse Breakdown Voltage	SD103BW $I_R = 10 \mu A$	$V_{(BR)}$	30	-	-	V
	SD103CW $I_R = 10 \mu A$		20			
Famurad Valtage	I _F = 20 mA	V	-	-	0.37	V
Forward Voltage	forward Voltage $I_F = 200 \text{ mA}$	V _F			0.60	
	SD103AW V _R = 30 V					
Reverse Leakage Current	SD103BW $V_R = 20 \text{ V}$	I _R	-	-	5	μA
	SD103CW $V_R = 10 \text{ V}$					
Junction Capacitance $V_R = 0$, $f = 1.0 \text{ MHz}$		CJ		50		pF

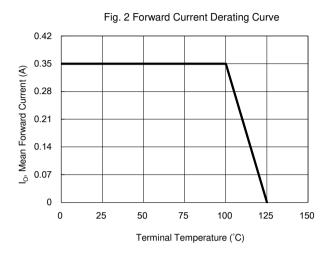


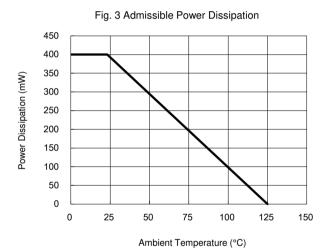
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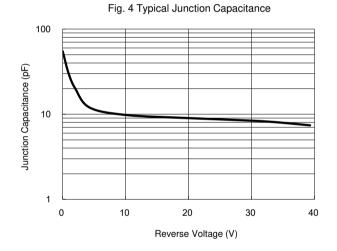
RATINGS AND CHARACTERISTICS CURVES

(T_A=25°C unless otherwise noted)











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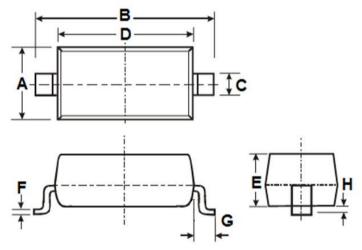
ORDERING INFORMATION				
PART NO.	PACKING CODE	PACKING CODE SUFFIX	PACKAGE	PACKING
SD103xW (Note 1, 2)	RH	G	SOD-123	3K / 7" Reel

Note 1: "x" is Device Code from "A" - "C". Note 2: Whole series with green compound

EXAMPLE				
EXAMPLE P/N	PART NO.	PACKING CODE	PACKING CODE SUFFIX	DESCRIPTION
SD103AW RHG	SD103AW	RH	G	Green compound

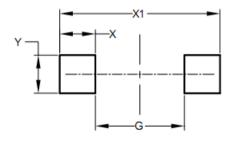
PACKAGE OUTLINE DIMENSIONS

SOD-123



DIM. Unit ((mm) Unit (inch)		(inch)
DIIVI.	Min	Max	Min	Max
Α	1.40	1.80	0.055	0.071
В	3.55	3.85	0.140	0.152
С	0.45	0.70	0.018	0.028
D	2.55	2.85	0.100	0.112
Е	0.95	1.35	0.037	0.053
F	0.05	0.15	0.002	0.006
G	0.50 REF		0.02	REF
Н	-	0.10	-	0.004

SUGGEST PAD LAYOUT



DIM.	Unit (mm)	Unit (inch)		
DIIVI.	Min	Min		
G	2.25	0.089		
Х	0.90	0.035		
X1	4.05	0.159		
Υ	0.95	0.037		

MARKING

Part No.	Marking
SD103AW	S4
SD103BW	S5
SD103CW	S6



Taiwan Semiconductor

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